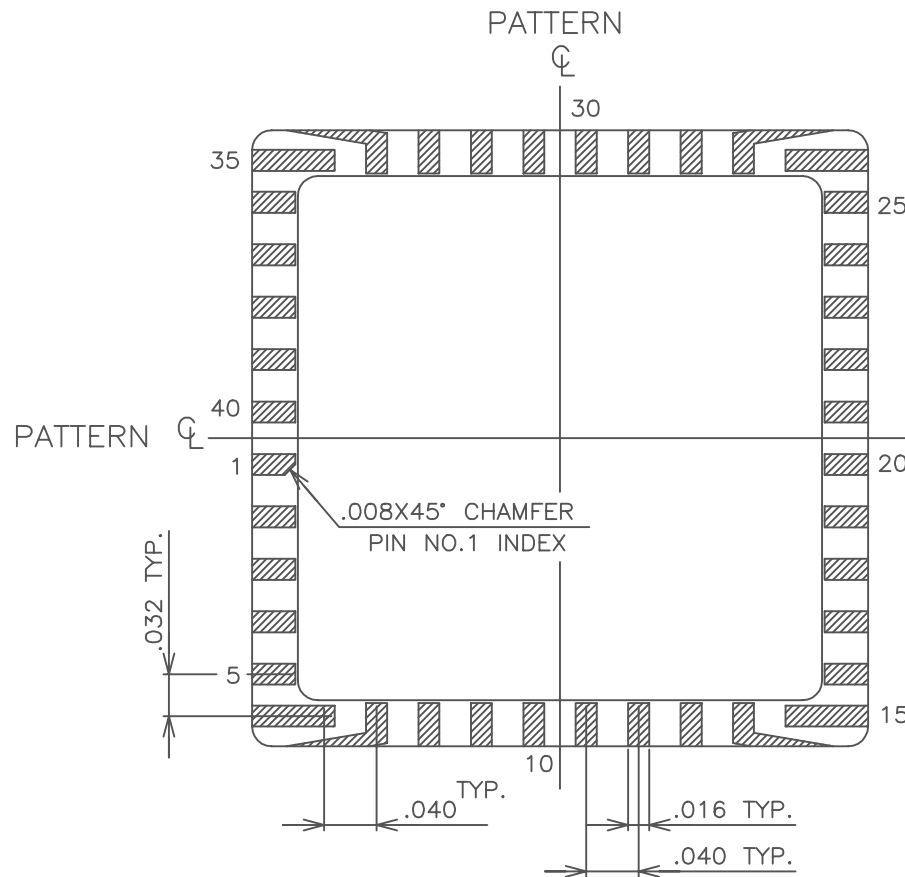


- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. TABS ON TIE-BAR OF LEAD FRAME SHALL BE REMOVED AT VENDOR'S OPTION.
 5. LEAD RESISTANCE : 0.50 OHMS MAX.

PART NO.	INDEX MARK	LEAD TIED DOWN		
03	40	PIN NO.40 ONLY	SBO40I302-3	S=0 D=40
02	△	PIN NO.1 ONLY	SBO40I302-2	S=0 D=1
01	□	NIL	SBO40I302-1	S=0 D=0

MODIFICATION						NAME	40 LEAD SIDE BRAZED PACKAGE		TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						SCALE	4 / 1	MATERIAL	UNLESS OTHERWISE SPECIFIED	T.A	K.M		JUL26'78
								AS INDICATED	±.005				
									THIRD ANGLE PROJECTION				
△	REDRAWN(CONVERTED CAD DATA)	MAR.27'96	Y.M	H.S/K.I	T.A			KYOCERA CORPORATION		DRAWING NO.	KD-78302-D		SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KYOTO JAPAN					1 / 2



BONDING PATTERN

MODIFICATION

CHANGED	DATE	DRAWN	CHECKED	APPROVED	

NAME 40 LEAD SIDE BRAZED PACKAGE

SCALE 10 / 1

TOLERANCE
UNLESS OTHERWISE SPECIFIED

THIRD ANGLE PROJECTION

DRAWN	CHECKED	APPROVED	DATE
T.A	K.M		JUL.26.'78



KYOCERA CORPORATION
KYOTO JAPAN

DRAWING NO.
KD-78302-D

SHEET
2/2